

### General Description

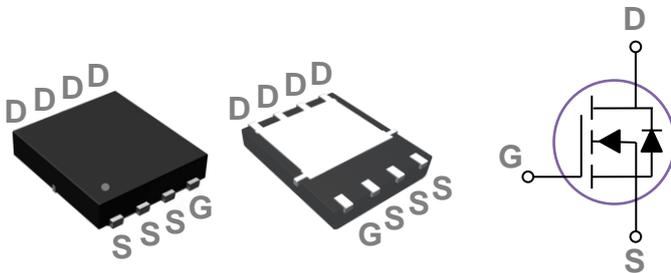
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
40V	7.6mΩ	60A

### Features

- 40V,60A, R<sub>DS(ON)</sub> =7.6mΩ @V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### PPAK5X6 Pin Configuration



### Applications

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

### Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	+20/-12	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	60	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	38	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	240	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	65	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	36	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	55	W
	Power Dissipation – Derate above 25°C	0.44	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	2.25	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V	---	---	100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =8A	---	6.3	7.6	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	---	10	13	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>S</sub> =1A	---	5	---	S

**Dynamic and switching Characteristics**

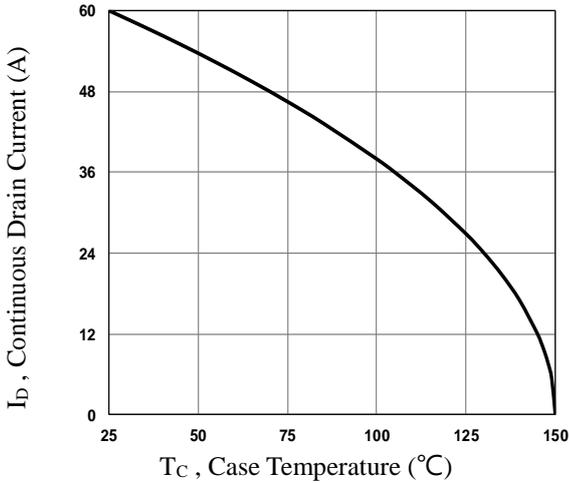
Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A	---	13.7	20	nC
			---	8	12	
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>	V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A	---	2.2	5	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	3.7	7	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =30A	---	10	15	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	14	21	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	28	42	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	20	30	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz	---	930	1400	pF
C <sub>oss</sub>	Output Capacitance		---	380	570	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	30	45	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	1	---	Ω

**Drain-Source Diode Characteristics and Maximum Ratings**

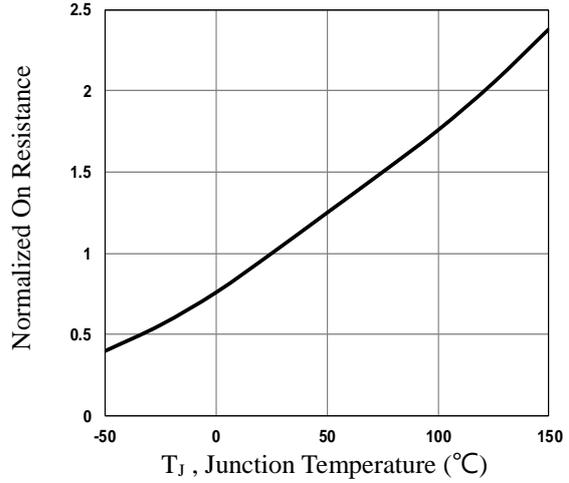
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	60	A
I <sub>SM</sub>	Pulsed Source Current		---	---	120	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
T <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =30V, I <sub>S</sub> =10A	---	45	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs T <sub>J</sub> =25°C	---	35	---	nC

Note :

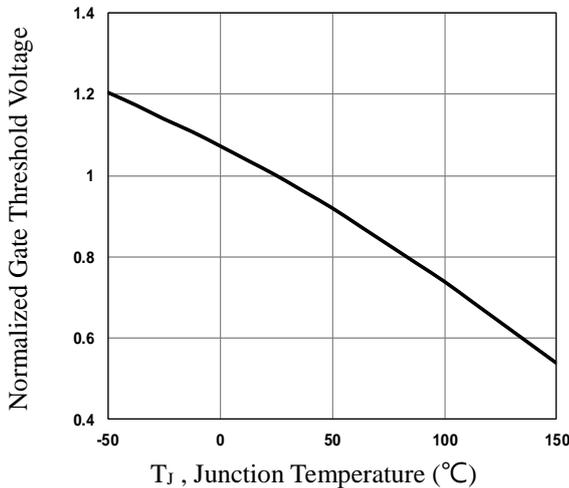
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=36A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



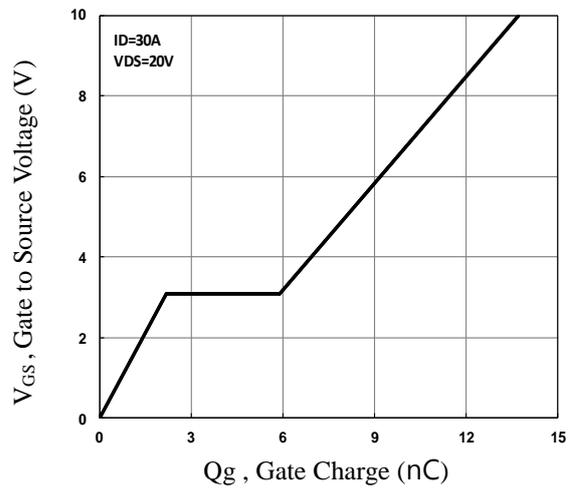
**Fig.1 Continuous Drain Current vs.  $T_c$**



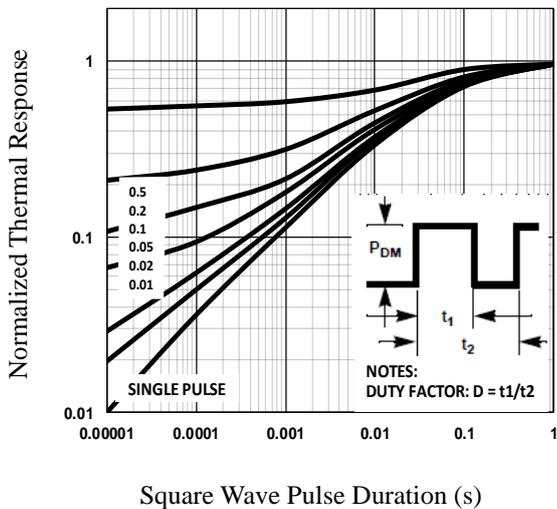
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



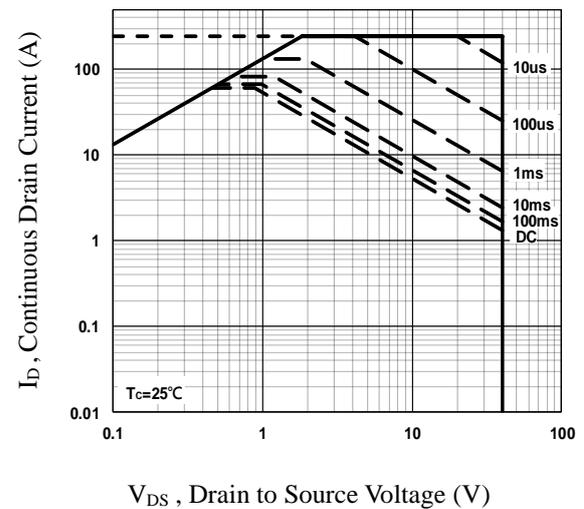
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



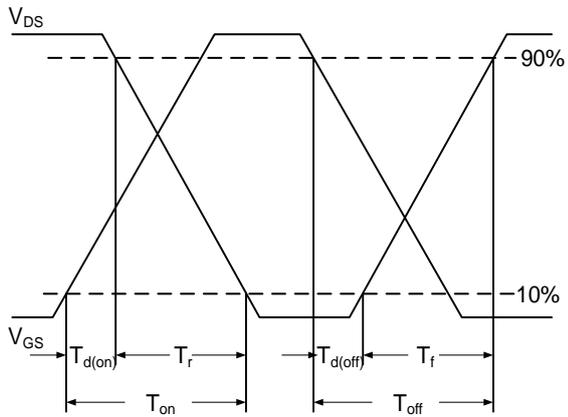
**Fig.4 Gate Charge Waveform**



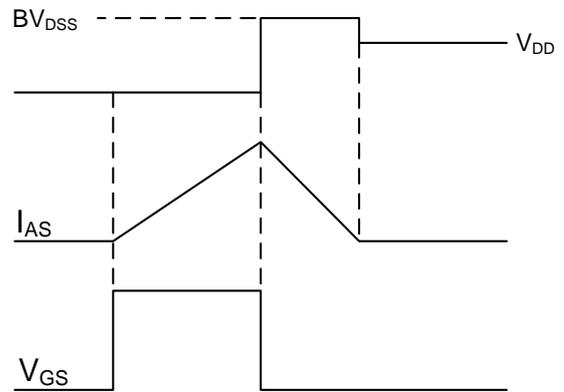
**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**



**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

**PPAK5x6 PACKAGE INFORMATION**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°